DATA SHEET



MINIATURE SIGNAL RELAY

EC2/EE2 SERIES

COMPACT SIZE, SLIM-PACKAGE

DESCRIPTION

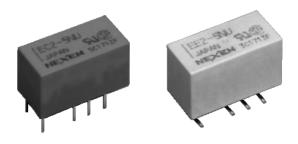
NEXEM EC2/EE2 relay is a standard miniature signal relay, compact and slim.

FEATURES

- □ Compact and light weight
- $\hfill\square\,$ FCC (1500 V) and Telcordia (2500 V) surge capacity
- □ UL recognized and CSA certified
- □ Low power consumption (100-230 mW)
- □ ND type (High insulation) conform to supplement insulation for EN62368-1
- □ NKX type (High breakdown voltage) can withstand 1.5KVAC at open contacts
- □ Moisture Barrier Bag (MBB) packaged EE2 relays meet moisture sensibility level (MSL) of IPC/JEDEC-STD-020.

APPLICATIONS

Electronic switching systems, PBX, Terminal equipment, Telephone system



For Right Use of Miniature Relays

DO NOT EXCEED MAXIMUM RATINGS.

Do not use relays under exceeding conditions such as over ambient temperature, over voltage and over current. Incorrect use could result in abnormal heating, damage to related parts or cause burning.

READ CAUTIONS IN THE SELECTION GUIDE.

Read the cautions described in EM Devices' "Miniature Relays" when you choose relays for your application.

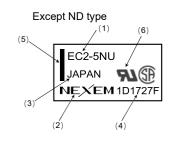
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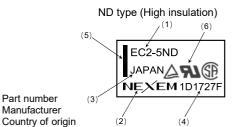
[mm]

MARKINGS (Top view)



STANDARD [TRIMMED LEAD] TYPE

Non-latch type, Single coil latch type HIGH INSULASION [TRIMMED LEAD] TYPE



(3)

(1)

(2)

7.5 max. (0.30)

5.08

Lead size 0.5 x 0.25 ± 0.1

Trimmed lead type: Lead length 2.8mm

Date code (4)

Direction mark (pin No. 1 and 12) (5) UL, CSA marking (TUV added for ND type) (6)

DIMENSIONS

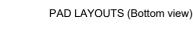
EC2 SERIES DIMENSIONS

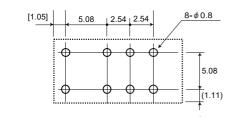
Non-latch type

15.0 max. (0.59)

5.08 2.54 2.54 is basic size.

Other tolerances ± 0.2mm





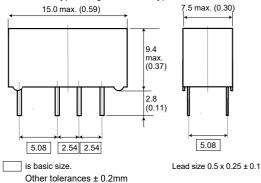
NOTE. General tolerance: ± 0.1

HIGH POWER SWITCHING AND TRIMMED LEAD TYPE Non-latch type, Single coil latch type

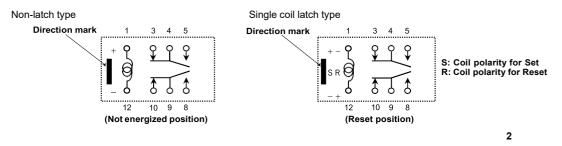
9.4

max. (0.37)

3.2 (0.13)

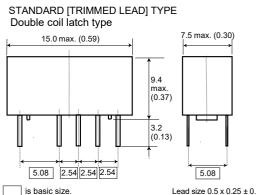


PIN CONFIGURATIONS (Bottom view)





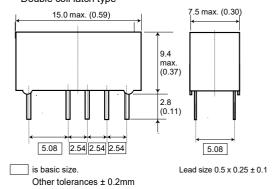
DIMENSIONS





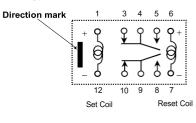
HIGH POWER SWITCHING AND TRIMMED LEAD TYPE Double coil latch type

Other tolerances ± 0.2mm

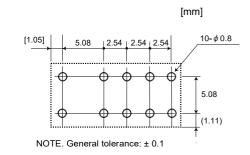


PIN CONFIGURATIONS (Bottom view)

Double coil latch type

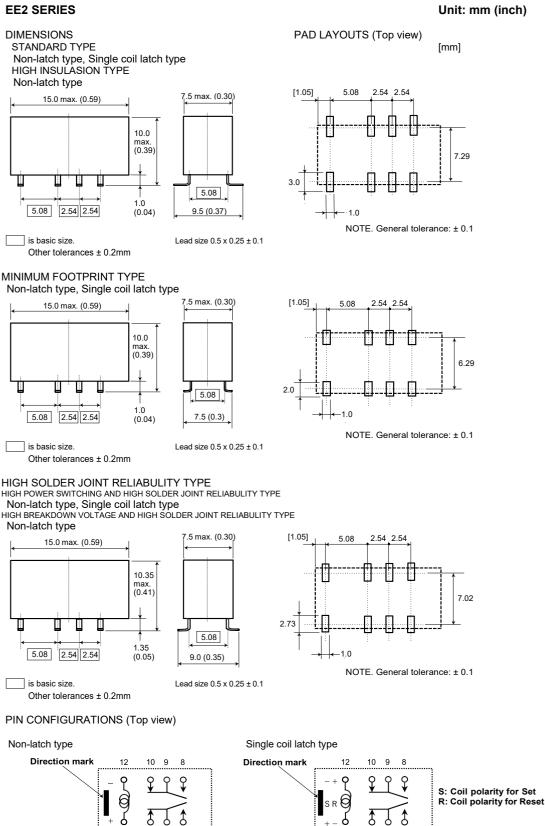


(Reset position)



PAD LAYOUTS (Bottom view)





4

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Before using the product in this catalog, please read "NOTES ON CORRECT USE" in the selection guide

9

9

5

3 4

(Reset position)

δ

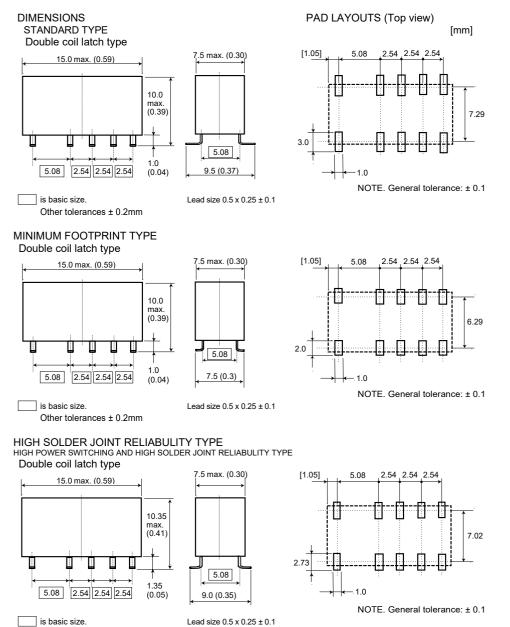
d

5

3

(Not energized position)

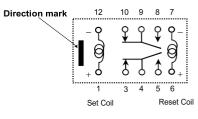




PIN CONFIGURATIONS (Top view)

Other tolerances ± 0.2mm

Double coil latch type



(Reset position)

5

GENERAL SPECIFICATIONS

		TICATIONS	25 0	
Contact Form			2 Form C	
Contact Mater	ial	Standard	Silver alloy with gold alloy overlay	
		High power switching type	Silver with gold alloy overlay	
Maximum Swit	tching	Standard	30 W, 62.5 VA (resistive)	
Power		High power switching type	60 W, 62.5 VA (resistive)	
Maximum Swit	tching V	oltage	220 VDC, 250 VAC	
Maximum Swit	tching C	urrent	2 A	
Maximum Carr	rying	Standard	2 A	
Current		High power switching type	3.2 A	
Minimum Cont	tact Rat	ngs	10 mVDC, 10μA	
Initial Contact	Resista	nce	$75 \text{ m} \Omega$ max.	
Operate Time [S	Set Time]	(Excluding bounce)	Approx. 2 ms [2ms]	
Release Time	[Reset	Time] (Excluding bounce)	Approx. 1 ms [2ms] (Without diode)	
Coil Temperat	ure Rise)	13 °C / 100mW, 18 °C / 140mW, 25 °C / 200mW, 28 °C / 230mW	
Insulation Res	istance		1000 MΩ at 500 VDC	
	Betwee	n Standard	1000 VAC (for one minute), 1500 V surge (10x160 µs *2)	
	open	High Breakdown	Break contact: 1000 VAC (for one minute), 1500 V surge (10x160 µs *2)	
	contac	s voltage (NKX) type	Make contact: 1500 VAC (for one minute), 2500 V surge (2x10 µs *3)	
	Betwee	n Standard	1000 VAC (for one minute), 1500 V surge (10x160 μs *2)	
Withstanding Voltage	adjace contac		1500 VAC (for one minute), 2500 V surge (2x10 µs *3)	
	Betwee coil an		1500 VAC (for one minute), 2500 V surge (2x10 µs *3)	
	contac	s Double coil latch type	1000 VAC (for one minute), 1500 V surge (10x160 µs *2)	
	Between set and reset coil		1000 VAC (for one minute) (Double coil latching type only)	
Oharah D. J. J.			735 m/s² (75G) (misoperation)	
Shock Resista	nce		980 m/s² (100G) (destructive failure)	
Vibration Resi	stance		10 to 55 Hz, double amplitude 3 mm (196 m/s ²) (misoperation)	
			10 to 55 Hz, double amplitude 5 mm (294 m/s ²) (destructive failure)	
Ambient Temp	erature		-40 to +85 °C	
	Non-l	oad	1x10 ⁸ operations (non-latch type) *4 1x10 ⁷ operations (latch type)	
Running			50 VDC 0.1A (resistive), 1x10 ⁶ operations at 85°C, 5Hz	
Specifications	Load		10 VDC 10mA (resistive), 1x10 ⁶ operations at 85°C, 2Hz	
	Γ	(Only High power switching type)	30 VDC 2A (resistive), 1x10 ⁵ operations at 23°C, 1Hz	
Weight			Approx. 1.9 g	
-				

* 1 This value is a reference value in the resistive load.

Minimum capacity changes depending on switching frequency and environment temperature and the load.

* 2 rise time: 10µs, decay time to half crest: 160µs

* 3 rise time: 2µs, decay time to half crest: 10µs

* 4 This shows the number of operations with fatal defects. Stable characteristics are maintained for 1 × 10⁷ operations.

at 20°C

COIL SPECIFICATIONS

Non-latch Type

Non-latch Type				al 20 C
Nominal	Coil	Must Operate	Must Release	Nominal
Coil Voltage	Resistance	Voltage*	Voltage*	Operating Power
(VDC)	(Ω)±10%	(VDC)	(VDC)	(mW)
3	64.3	2.25	0.3	140
4.5	145	3.38	0.45	140
5	178	3.75	0.5	140
9	579	6.75	0.9	140
12	1028	9.0	1.2	140
24	2880	18.0	2.4	200

Single Coil Latch Type

Single Coil Latch Type	9			at 20°C
Nominal	Coil	Set	Reset	Nominal
Coil Voltage	Resistance	Voltage*	Voltage*	Operating Power
(VDC)	(Ω)±10%	(VDC)	(VDC)	(mW)
3	90	2.25	2.25	100
4.5	202.5	3.38	3.38	100
5	250	3.75	3.75	100
9	810	6.75	6.75	100
12	1440	9.0	9.0	100
24	5760	18.0	18.0	100

Note: Apply the coil voltage so that the No.1 pin is on the + side when set and the No.12 pin is on the + side when reset.

Double Coil Latch Type (Can not be driven by reverse polarity for reverse operation) at 20°C					
Nominal	Coil		Must Operate	Must Release	Nominal
Coil Voltage	Resist	ance	Voltage*	Voltage*	Operating Power
(VDC)	(Ω)±´	10%	(VDC)	(VDC)	(mW)
3	S	64.3	2.25	-	140
3	R	64.3	-	2.25	140
4.5	S	145	3.38	-	140
4.5	R	145	-	3.38	140
5	S	178	3.75	-	140
5	R	178	-	3.75	140
9	S	579	6.75	-	140
9	R	579	-	6.75	140
40	S	1028	9.0	-	140
12	R	1028	-	9.0	140
	S	4114	18.0	-	140
24	R	4114	-	18.0	140

Note: S: Set coil (pin No.1 ... (+), pin No.12 ... (-)) R: Reset coil (pin No.6... (+), pin No.7... (-))

Non-latch High Insulation (ND) Type

Non-latch High Insula	tion (ND) Type			at 20°C
Nominal	Coil	Must Operate	Must Release	Nominal
Coil Voltage	Resistance	Voltage*	Voltage*	Operating Power
(VDC)	(Ω)±10%	(VDC)	(VDC)	(mW)
3	45	2.25	0.3	200
4.5	101	3.38	0.45	200
5	125	3.75	0.5	200
9	405	6.75	0.9	200
12	720	9.0	1.2	200
24	2504	18.0	2.4	230

7



Non-latch High Breakdown Voltage (NKX) Type

N	Ion-latch High Break	down Voltage (NKX) Ty	/pe		at 20°C
Γ	Nominal	Coil	Must Operate	Must Release	Nominal
	Coil Voltage	Resistance	Voltage*	Voltage*	Operating Power
	(VDC)	(Ω)±10%	(VDC)	(VDC)	(mW)
	3	39.1	2.25	0.3	230
	4.5	88.0	3.38	0.45	230
	12	626	9.0	1.2	230

Note: * Test by pulse voltage ** The latch type relays should be initialized at appointed position before using by avoid wrong operation.

SAFETY STANDARD AND RATING

UL Rec (UL5 File No	CSA Certificated (CSA C22.2 No14) File No LR46266		
Standard	High power switching type		
30 VDC, 2 A (Resistive) 110 VDC, 0.3 A (Resistive) 125 VAC, 0.5 A (Resistive)	30 VDC, 3 A (Resistive) 110 VDC, 0.3 A (Resistive) 125 VAC, 0.5 A (Resistive)	30 VDC, 2 A (Resistive) 110 VDC, 0.3 A (Resistive) 125 VAC, 0.5 A (Resistive)	

* Spacing: UL114, UL478

TUV Certificate (IEC61810-1/EN61810-1)				
File No. R9751153** File No. R9750561				
NU, NJ, NUH, NUX Type	ND Type			
(Non-latch and Single coil latch)	(Non-latch)			
Creepage and clearance of coil to contact is more than 2 mm. (According to EN62368-1)				
Basic insulation class Supplementary insulation class				

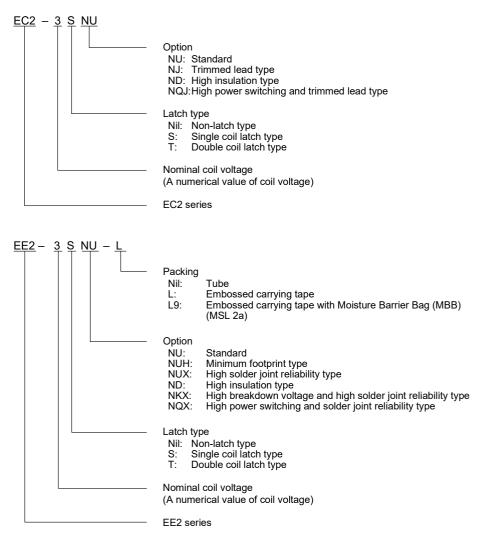
**High power switching type are not supported TUV certified.

RECOMMENDED RELAY DRIVE CONDITIONS

Drive under conditions.

Non-latch type	Voltage: within ±5% of nominal voltage	Ambient temperature
Single coil latch type Double coil latch type	Square pulse (rise and fall time is rapid) pulse height: within ±5% of nominal voltage pulse width: more than 10 ms	- 40 to +85 °C

PART NUMBER SYSTEM





ORDERING PART NUMBERS

EC2 series

Option		Nominal Coil Voltage	Coil Type			
Terminal	Packing	(VDC)	Non-latch	Single Coil Latch	Double Coil Latch	
		3	EC2-3NU	EC2-3SNU	EC2-3TNU	
		4.5	EC2-4.5NU	EC2-4.5SNU	EC2-4.5TNU	
Standard		5	EC2-5NU	EC2-5SNU	EC2-5TNU	
Standard	- Tube	9	EC2-9NU	EC2-9SNU	EC2-9TNU	
		12	EC2-12NU	EC2-12SNU	EC2-12TNU	
		24	EC2-24NU	EC2-24SNU	EC2-24TNU	
		3	EC2-3NJ	EC2-3SNJ	EC2-3TNJ	
		4.5	EC2-4.5NJ	EC2-4.5SNJ	EC2-4.5TNJ	
Trimmed			5	EC2-5NJ	EC2-5SNJ	EC2-5TNJ
lead		9	EC2-9NU	EC2-9SNU	EC2-9TNU	
		12	EC2-12NJ	EC2-12SNJ	EC2-12TNJ	
		24	EC2-24NJ	EC2-24SNJ	EC2-24TNJ	

□ EC2 series High Insulation Type (ND Type)

Option		Nominal Coil Voltage	Coil Type	
Terminal	Packing	(VDC)	Non-latch	
		3	EC2-3ND	
	Tube		4.5	EC2-4.5ND
Standard		5	EC2-5ND	
Standard		9	EC2-9ND	
		12	EC2-12ND	
			24	EC2-24ND

EC2 series High Power Switching Type (NQJ Type)

Option		Nominal Coil Voltage	Coil Type		
Terminal	Packing	(VDC)	Non-latch	Single Coil Latch	Double Coil Latch
	Tube	3	EC2-3NQJ	EC2-3SNQJ	EC2-3TNQJ
Trimmed lead		4.5	EC2-4.5NQJ	EC2-4.5SNQJ	EC2-4.5TNQJ
		5	EC2-5NQJ	EC2-5SNQJ	EC2-5TNQJ
		9	EC2-9NQJ	EC2-9SNQJ	EC2-9TNQJ
		12	EC2-12NQJ	EC2-12SNQJ	EC2-12TNQJ
		24	EC2-24NQJ	EC2-24SNQJ	EC2-24TNQJ



Option		Nominal Coil Voltage Coil Type			
Terminal	Packing	(VDC)	Non-latch	Single Coil Latch	Double Coil Latch
		3	EE2-3NU	EE2-3SNU	EE2-3TNU
		4.5	EE2-4.5NU	EE2-4.5SNU	EE2-4.5TNU
	Tube	5	EE2-5NU	EE2-5SNU	EE2-5TNU
	Tube	9	EE2-9NU	EE2-9SNU	EE2-9TNU
		12	EE2-12NU	EE2-12SNU	EE2-12TNU
		24	EE2-24NU	EE2-24SNU	EE2-24TNU
	Taping	3	EE2-3NU-L	EE2-3SNU-L	EE2-3TNU-L
		4.5	EE2-4.5NU-L	EE2-4.5SNU-L	EE2-4.5TNU-L
		5	EE2-5NU-L	EE2-5SNU-L	EE2-5TNU-L
Standard		9	EE2-9NU-L	EE2-9SNU-L	EE2-9TNU-L
		12	EE2-12NU-L	EE2-12SNU-L	EE2-12TNU-L
		24	EE2-24NU-L	EE2-24SNU-L	EE2-24TNU-L
		3	EE2-3NU-L9	EE2-3SNU-L9	EE2-3TNU-L9
		4.5	EE2-4.5NU-L9	EE2-4.5SNU-L9	EE2-4.5TNU-L9
	Taping	5	EE2-5NU-L9	EE2-5SNU-L9	EE2-5TNU-L9
	(MBB)	9	EE2-9NU-L9	EE2-9SNU-L9	EE2-9TNU-L9
	()	12	EE2-9NU-L9	EE2-93NU-L9 EE2-12SNU-L9	EE2-12TNU-L9
		24	EE2-24NU-L9	EE2-123NU-L9 EE2-24SNU-L9	EE2-24TNU-L9
		3	EE2-3NUH	EE2-3SNUH	
		4.5			EE2-3TNUH
	Tube		EE2-4.5NUH	EE2-4.5SNUH	EE2-4.5TNUH
		5	EE2-5NUH	EE2-5SNUH	EE2-5TNUH
		9	EE2-9NUH	EE2-9SNUH	EE2-9TNUH
		12	EE2-12NUH	EE2-12SNUH	EE2-12TNUH
-		24	EE2-24NUH	EE2-24SNUH	EE2-24TNUH
		3	EE2-3NUH-L	EE2-3SNUH-L	EE2-3TNUH-L
Minimum		4.5	EE2-4.5NUH-L	EE2-4.5SNUH-L	EE2-4.5TNUH-L
	Taping	5	EE2-5NUH-L	EE2-5SNUH-L	EE2-5TNUH-L
footprint		9	EE2-9NUH-L	EE2-9SNUH-L	EE2-9TNUH-L
		12	EE2-12NUH-L	EE2-12SNUH-L	EE2-12TNUH-L
-		24	EE2-24NUH-L	EE2-24SNUH-L	EE2-24TNUH-L
	Taping (MBB)	3	EE2-3NUH-L9	EE2-3SNUH-L9	EE2-3TNUH-L9
		4.5	EE2-4.5NUH-L9	EE2-4.5SNUH-L9	EE2-4.5TNUH-L9
		5	EE2-5NUH-L9	EE2-5SNUH-L9	EE2-5TNUH-L9
		9	EE2-9NUH-L9	EE2-9SNUH-L9	EE2-9TNUH-L9
		12	EE2-12NUH-L9	EE2-12SNUH-L9	EE2-12TNUH-L9
		24	EE2-24NUH-L9	EE2-24SNUH-L9	EE2-24TNUH-L9
		3	EE2-3NUX	EE2-3SNUX	EE2-3TNUX
	Tube	4.5	EE2-4.5NUX	EE2-4.5SNUX	EE2-4.5TNUX
		5	EE2-5NUX	EE2-5SNUX	EE2-5TNUX
		9	EE2-9NUX	EE2-9SNUX	EE2-9TNUX
		12	EE2-12NUX	EE2-12SNUX	EE2-12TNUX
		24	EE2-24NUX	EE2-24SNUX	EE2-24TNUX
Γ		3	EE2-3NUX-L	EE2-3SNUX-L	EE2-3TNUX-L
		4.5	EE2-4.5NUX-L	EE2-4.5SNUX-L	EE2-4.5TNUX-L
High Solder	Taping	5	EE2-5NUX-L	EE2-5SNUX-L	EE2-5TNUX-L
pint reliability		9	EE2-9NUX-L	EE2-9SNUX-L	EE2-9TNUX-L
		12	EE2-12NUX-L	EE2-12SNUX-L	EE2-12TNUX-L
		24	EE2-24NUX-L	EE2-24SNUX-L	EE2-24TNUX-L
		3	EE2-3NUX-L9	EE2-3SNUX-L9	EE2-3TNUX-L9
	Tasias	4.5	EE2-4.5NUX-L9	EE2-4.5SNUX-L9	EE2-4.5TNUX-L9
		5	EE2-5NUX-L9	EE2-5SNUX-L9	EE2-5TNUX-L9
	Taping (MBB)	9			
	(100)	9	EE2-9NUX-L9	EE2-9SNUX-L9	EE2-9TNUX-L9
		12	EE2-12NUX-L9	EE2-12SNUX-L9	EE2-12TNUX-L9

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EE2 series High Insulation Type (ND Type)

Option		Nominal Coil Voltage	Coil Type	
Terminal	Packing	(VDC)	Non-latch	
	Tube	3	EE2-3ND	
		4.5	EE2-4.5ND	
		5	EE2-5ND	
		9	EE2-9ND	
		12	EE2-12ND	
		24	EE2-24ND	
	Taping	3	EE2-3ND-L	
		4.5	EE2-4.5ND-L	
Chandend		5	EE2-5ND-L	
Standard		9	EE2-9ND-L	
		12	EE2-12ND-L	
		24	EE2-24ND-L	
	4.5 EE2-4 Taping (MBB) 5 EE2- 9 EE2- 12 EE2-1	3	EE2-3ND-L9	
		4.5	EE2-4.5ND-L9	
		5	EE2-5ND-L9	
		EE2-9ND-L9		
		12	EE2-12ND-L9	
		24	EE2-24ND-L9	

□ EE2 series High Breakdown Voltage Type (NKX Type)

Option		Nominal Coil Voltage	Coil Type	
Terminal	Packing	(VDC)	Non-latch	
	Tube	3	EE2-3NKX	
		4.5	EE2-4.5NKX	
		12	EE2-12NKX	
	Taping	3	EE2-3NKX-L	
High Solder joint reliability		4.5	EE2-4.5NKX-L	
		12	EE2-12NKX-L	
		3	EE2-3NKX-L9	
	Taping (MBB)	4.5	EE2-4.5NKX-L9	
	· · /	12	EE2-12NKX-L9	

□ EE2 series High Power Switching Type (NQX Type)

Option		Nominal Coil Voltage	Coil Туре		
Terminal	Packing	(VDC)	Non-latch	Single Coil Latch	Double Coil Latch
	Taping (MBB)	3	EE2-3NQX-L9	EE2-3SNQX-L9	EE2-3TNQX-L9
		4.5	EE2-4.5NQX-L9	EE2-4.5SNQX-L9	EE2-4.5TNQX-L9
High Solder joint reliability		5	EE2-5NQX-L9	EE2-5SNQX-L9	EE2-5TNQX-L9
		9	EE2-9NQX-L9	EE2-9SNQX-L9	EE2-9TNQX-L9
		12	EE2-12NQX-L9	EE2-12SNQX-L9	EE2-12TNQX-L9
		24	EE2-24NQX-L9	EE2-24SNQX-L9	EE2-24TNQX-L9

Note:

1.

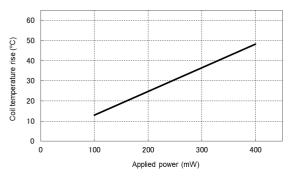
Only MBB packaging part numbers meet MSL (L9: MSL 2a). However, it does not fully conform to JEDEC standards such as classification temperature. Please note that part numbers other without MBB packaging do not meet MSL. The packaging specification for EE2 relay high power switching type is only Taping with MBB (MSL 2a). Please note that other packaging specifications are not supported. 2.

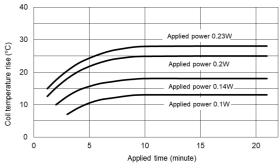


PERFORMANCE DATA

COIL TEMPERATURE RISE

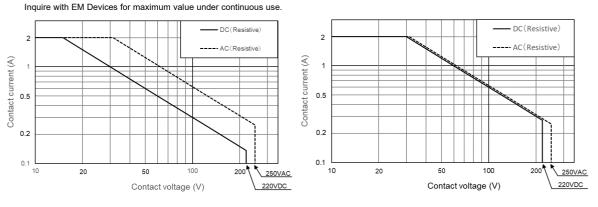
Temperature is measured by coil resistance.





□SWITCHING CAPACITY

This is allowed maximum value.



(Standard)

(High power switching type)

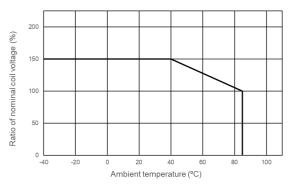
13



□MAXIMUM COIL VOLTAGE

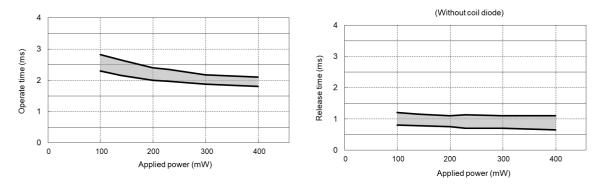
This is a maximum value of permissible alteration.

Inquire with EM Devices under continuous use.





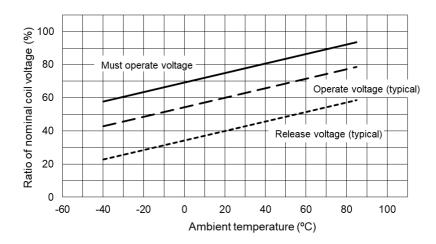
(Sample: EC2-5NU)





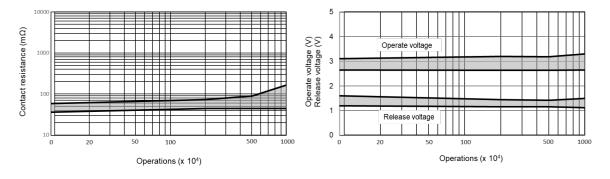
OPERATE AND RELEASE VOLTAGE VS. AMBIENT TEMPERATURE

This shows a typical change of operate (release) voltage. The value of must operate is estimated, so coil voltage must be applied more than this value for safety operation. For hot start operation, please inquire with EM Devices.



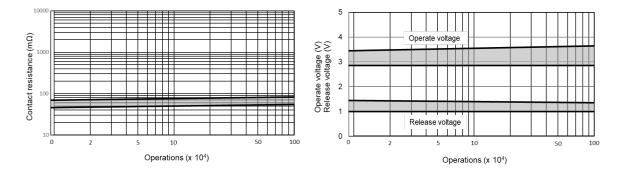
□RUNNING TEST (Non-load)

(Load: none, Drive: 5VDC, 50Hz, 50%duty, Ambient temperature: room temperature, Sample: EC2-5NU, 20pieces)



□RUNNING TEST (Load)

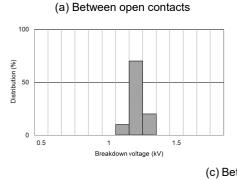
(Load: 50VDC 0.1A resistive, Drive: 5VDC, 5Hz, 50%duty, Ambient temperature: 85°C, Sample: EC2-5NU, 10pieces)

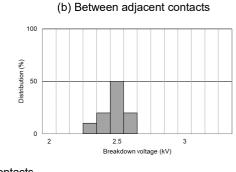


□BREAKDOWN VOLTAGE

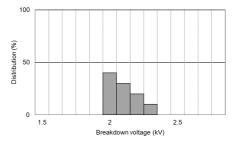
NEXEM

Sample: EC2-5NU 10peices

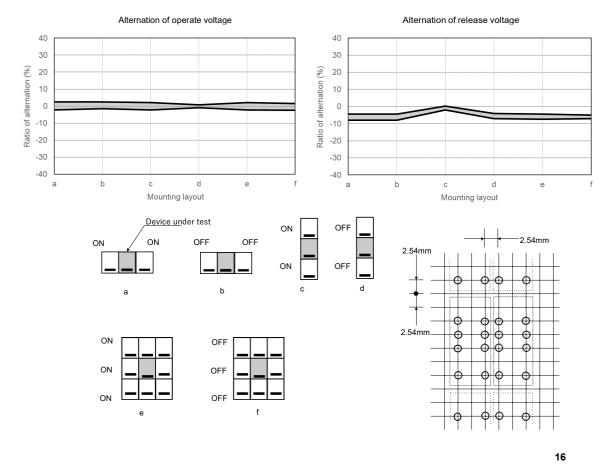




(c) Between coil and contacts



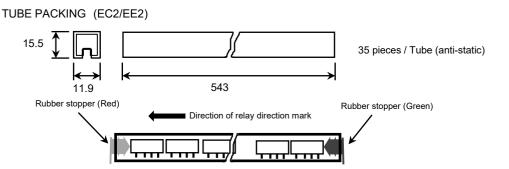
ALTERNATION OF VOLTAGE AT DENSELY MOUNTING (Magnet interference)



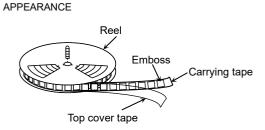


PACKING DIMENSIONS

(Unit: mm)

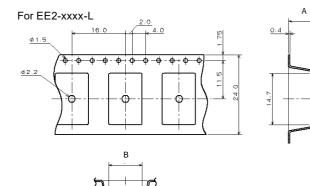


TAPE PACKING (EE2)

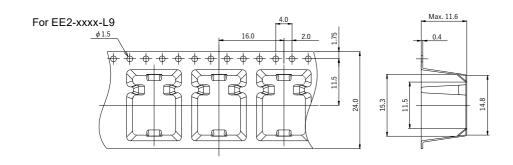


Corrugated Cardboard (L) PS (L9: MBB) Reel material: 500 pieces / Reel L9 has two reels are sealed in one MBB. Relay quantity: Reel diameter: 380mm

TAPE DIMENSIONS



	А	В
EE2-xxNU-L		
EE2-xxND-L	Max.10.9	10.0
EE2-xxNUX-L	Wax. 10.9	10.0
EE2-xxNKX-L		
EE2-xxNUH-L	Max.11.1	8.0



7.8

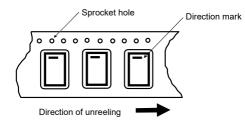
10.6

Note. Changes in the tape geometry may require adjustments to the mounted machine.

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RELAY DIRECTION AND TAPE CARRYING DIRECTION



SOLDERING TEMPERATURE CONDITION

THROUGH-HOLE MOUNTING (EC2)

1. Automatic soldering

Preheating: 110~ 120°C /110 s. (max.) Solder temperature: 260°C max. Solder time: 5 s max.

Note: EM Devices recommends cooling down a printed circuit board less than 110°C within 40 s after soldering.

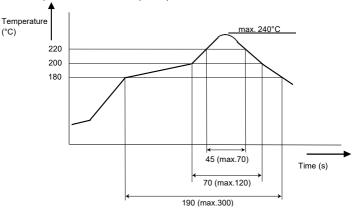
2. Manual soldering

Solder temperature: 350°C max. Solder time: 3 s max.

Note: Heating of this product by automatic soldering and manual soldering is limited to a total of three times.

SURFACE-MOUNTING TYPE (EE2)

1. Reflow Method (NEXEM recommend profile)



Note:

1. Temperature profile shows printed circuit board surface temperature on the relay terminal portion.

2. Heating by reflow should be limited to two times. However, allow sufficient time for cooling of the product between the first and second reflow.

3. Check the actual soldering condition to use other method except above mentioned temperature profiles.

NOTE ON CORRECT USE

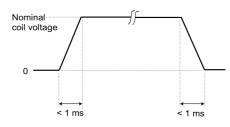
1. Notes on contact load

Make sure that the contact load is within the specified range; otherwise, the lifetime of the contacts will be shortened considerably.

Note that the running performance shown is an example, and that it varies depending on parameters such as the type of load, switching frequency, driver circuit, and ambient temperature under the actual operating conditions. Evaluate the performance by using the actual circuit before using the relay.

2. Driving relays

- If the internal connection diagram of a relay shows + and symbols on the coil, apply the rated voltage to the relay in the specified direction. If a rippled DC current source is used, abnormalities such as beat at the coil may occur.
- The maximum voltage that can be applied to the coil of the relay varies depending on the ambient temperature. Generally, the higher the voltage applied to the coil, the shorter the operating time. Note, however, that a high voltage also increases the bounce of the contacts and the contact opening and closing frequency, which may shorten the lifetime of the contacts.
- If the driving voltage waveform of the relay coil rises and falls gradually, the inherent performance of the relay may not be fully realized. Make sure that the voltage waveform instantaneously rises and falls as a pulse.

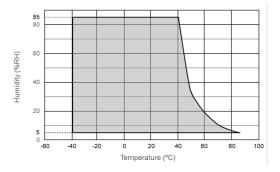


- For a latching relay, apply a voltage to the coil according to the polarity specified in the internal connection diagram of the relay.
- If a current is applied to the coil over a long period of time, the coil temperature rises, promoting generation of organic gas inside the relay, which may result in faulty contacts. In this case, use of a latching relay is recommended.
- The operating time and release time indicate the time required for each contact to close after the voltage has been applied to or removed from the coil. However, because the relay has a mechanical structure, a bounce state exists at the end of the operating and release times. Furthermore, because additional time is required until the contact stabilizes after being in a high-resistance state, care must be taken when using the relay at high speeds.

3. Operating environment

 Make sure that the relay mounted in the application set is used within the specified temperature range. Use of a relay at a temperature outside this range may adversely affect insulation or contact performance.

- If the relay is used for a long period of time in highly humid (RH 85% or higher) environment, moisture may be absorbed into the relay. This moisture may react with the NOx and SOx generated by glow discharges that occur when the contacts are opened or closed, producing nitric or sulfuric acid. If this happens, the acid produced may corrode the metallic parts of the relay, causing operational malfunction.
- If any material containing silicone (silicone rubber, silicone oil, and silicone-based coating material) is used in the neighborhood of relay, there is some possibility that these materials will emit silicone gas that will penetrate the relay. In this case, the switching contact may generate silicon compounds on the surface of contacts. This silicon compound may result in contact failure. Avoid use of relay in such an environment.
- Because the operating temperature range varies depending on the humidity, use the relay in the temperature range illustrated in the figure below. Prevent the relay from being frozen and avoid the generation of condensation.



- The same applies when the relay is stored or transported.
 Keep the upper-limit value of the temperature to which the relay is exposed after it is removed from the carton box to within 50°C. Please also refer to "5. Handling" for SMT relays.
- Permanent magnets are used in polarized relays. For this reason, when magnets, transformers, or speakers are located nearby the relay characteristics may change and faulty operations may result.
- The relay maintains constant sealability under normal atmospheric pressure (810 to 1,200 hPa). Its sealability may be degraded or the relay may be deformed and malfunction if it is used under barometric conditions exceeding the specified range.
- If excessive vibration or shock is applied to the relay, it may malfunction, and the contacts remain closed.
 Vibration or shock applied to the relay during operation may cause considerable damage to or wearing of the contacts. Note that operation of a snap switch mounted close to the relay or shock due to the operation of magnetic solenoid may also cause malfunctioning.

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4. Notes on mounting relays

- When mounting a relay onto a PC board using an automatic chip mounter, if excessive force is applied to the cover of the relay when the relay is chucked or inserted, the cover may be damaged, or the characteristics of the relay degraded. Keep the force applied to the relay to within 1 kg.
- Avoid bending the pins to temporarily secure the relay to the PC board. Bending the pins may degrade sealability or adversely affect the internal mechanism.
- It is recommended to solder the relay onto a PC board under the following conditions:
 - <1> Reflow soldering
 - Refer to the recommended soldering temperature profile. Please note that excessive heating beyond the specified peak temperature or heating time will damage the airtightness.
 - <2> Flow soldering

Solder temperature: 260°C max., Time: 5 s max.

Preheating: 110~ 120°C /110 s. (max.)

EM Devices recommends cooling down a printed circuit board less than 110° C within 40 seconds after soldering.

<3> Manual soldering

Solder temperature: 350°C, Time: 3 s max.

Avoid immersing the relay in cleaning solvent immediately after soldering due to the danger of thermal shock being applied to the relay.

- Use an alcohol-based or water-based cleaning solvent. Never use thinner and benzene because they may damage the relay housing.
- Do not use ultrasonic cleaning because the vibration energy generated by the ultrasonic waves may cause the contacts to remain closed.
- 5. <u>Handling</u>
- Relays are packaged in magazine cases for shipment. If a space is created in the case after some relays have been removed, be sure to insert a stopper to secure the remaining relays in the case. If relays are not well secured, vibration during transportation may cause malfunctioning of the contacts.
- Exercise care in handling the relay so as to avoid dropping it or allowing it to fall. Do not use a relay that has been dropped.
 If a relay drops from a workbench to the floor, a shock of 9,800 m/s² (1,000 G) or more is applied to the relay, possibly damaging its functions. Even if a light shock has been applied to the relay, thoroughly evaluate its operation before using it.
- Latching relays are factory-set to the reset state for shipment.
 A latching relay may be set, however, by vibration or shock applied while being transported. Be sure to forcibly reset the relay before using it in the application set. Also note that the relay may be set by unexpected vibration or shock when it is used in a portable set.

- The sealability of a surface mount type (SMT) relay may be lost if the relay absorbs moisture and is then heated during soldering. When storing relays, therefore, observe the following points:
 - <1> For standard packing
 - (a). Pack state
 - Term: Less than 12 months after our shipment. (Recommend using the product as soon as possible.)

Conditions: <30 °C, <60% RH

- (b). Require bake before mounting, when relays not used within the above (a) period or was stored outside above (a) conditions.
 - Simple relay: Please dehumidify 85 ± 5 °C, 48 hours or more after transferring to a heat-resistant container.
 - Tape packing: Please dehumidify 50 ± 5 °C, 300 hours or more in reel condition.

Tube packaging should be baking on simple relays, removed from tube.

Relays after baking should be mounted within 3 months under the conditions in (a).

Standard packaging specification products do not meet with the JEDEC standard's Moisture Sensitivity Level (MSL) because they are not MBB packaged. If MSL compliance is required, use MBB packaging specification products.

- <2> For MBB packing
 - (a). MBB state
 - Term: Less than 12 months after our shipment Conditions: <30 °C, <60% RH
 - (b). After opening of MBB
 - Term: Within the time limit indicated on the caution label attached to MBB.
 - Conditions: <30 °C, <60% RH
 - (c). Require bake before mounting, when relays not used within the above (a) or (b) period or was stored outside above conditions.
 - Simple relay: Please dehumidify 85 ± 5 °C, 48 hours or more after transferring to a heat-resistant container.
 - Tape packing: Please dehumidify 50 ± 5 °C, 300 hours or more in reel condition. Please keep in mind that barrier pack needs to remove in that case.

Relays after baking should be mounted within the time limits according to MSL on the caution label under the conditions in (b).

The humidity indicator card included in MBB package immediately after opening should also be used as a basis for judging baking procedures.

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●Before using the product in this catalog, please read "NOTES ON CORRECT USE" in the selection guide

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(Note)

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